



Drill Map:

- × 0.457mm / 0.0180" (18 holes)
- 1.000mm / 0.0394" (66 holes)
- + 1.067mm / 0.0420" (4 holes)
- ◊ 2.200mm / 0.0866" (2 holes) (not plated)
- ◻ 1.850mm / 0.0728" (2 holes) (not plated)
- ⊠ 3.400mm / 0.1339" (4 holes) (not plated)
- \* 3.500mm / 0.1378" (4 holes) (not plated)

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	62.99 mils
Board overall dimensions:	2755.91 mils x 2086.61 mils		
Min track/spacing:	12.00 mils / 10.00 mils	Min hole diameter:	11.81 mils
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		